

**Industrial Temperature Rating**  
-40° to +85° C

**Broad Certifications with Multiple Antennas**  
FCC (USA), IC (Canada), ETSI (Europe),  
Giteki (Japan), and RCM (AU/NZ)

**On-Module Chip Antenna Available**

- Offers greater resistance to de-tuning vs. trace or standard chip antennas
- Larger pin outs simplify manufacturing assembly

# Sterling-LWB™

## 2.4 GHz Wi-Fi® and Bluetooth® Smart Ready Multi-Standard Module



Actual Size (15.5mm x 21mm)

### FEATURES AND BENEFITS

- Delivers IEEE 802.11 b/g/n, BT 2.1+EDR, and BLE 4.1 wireless connectivity
- Based on next-generation silicon from Cypress (CYW4343W)
- Three versions of the module available:
  - SiP without antenna (10 mm x 10 mm x 1.2 mm)
  - With chip antenna (15.5 mm x 21 mm x 2 mm)
  - With external U.FL antenna port (15.5 mm x 21 mm x 2 mm)
- Enhanced collaborative co-existence algorithms
- Nearly 60% lower Active Rx Power Consumption (vs TiWi-BLE)
- Latest Linux and Android drivers supported directly by LSR
- NEW: **Sterling-LWB for WICED™** reference platform available for embedded MCU applications
- SIG certified Bluetooth driver (QDID: 64781)
- Multiple certified 2.4 GHz antenna options  
Chip, Dipole, FlexPIFA™ & FlexNotch™  
LSR offers in-house certification of additional antennas at little to no cost

### Practical Applications:

Security & Building Automation, Internet of Things / M2M Connectivity, Smart Gateways



a Laird Business

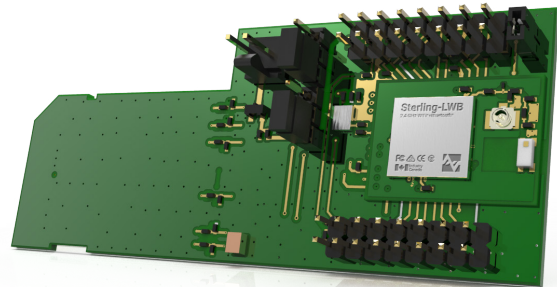
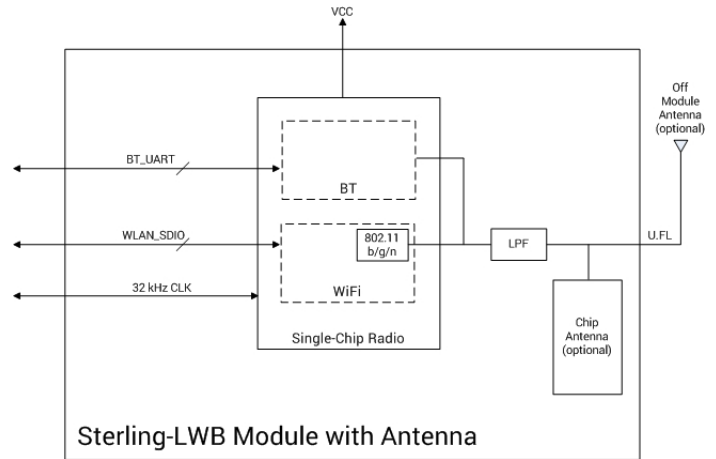
## STERLING-LWB MODULE PERFORMANCE

SPECIFICATION	VALUE
Operating Temp	-40 to +85° C
Operating Voltage	3.0 V to 3.6 V
WLAN Transmit Power	802.11b, 11 Mbps CCK: 17.5 dBm 802.11g, 54 Mbps rate: 14.0 dBm 802.11n, 65 Mbps MCS7: 12.5 dBm
WLAN Rx Sensitivity	802.11b, 11 Mbps CCK: -88 dBm 802.11g, 54 Mbps rate: -75 dBm 802.11n, 65 Mbps MCS7: -72 dBm
Bluetooth Transmit Power	8.5 dBm (GFSK)
Bluetooth Rx Sensitivity	-90 dBm (GFSK)

All specifications are preliminary and subject to change.

## ORDER INFORMATION

PART NUMBER	DESCRIPTION
450-0152	Sterling-LWB Chip Antenna Module
450-0148	Sterling-LWB U.FL Module
450-0159	Sterling-LWB Base Module (SiP)
450-0155	Sterling-LWB Development Board w/ U.FL
450-0156	Sterling-LWB Development Board w/ Chip Antenna
450-0173	Sterling-LWB for WICED™ Carrier Board



Dev Board with SD card form factor (Part # 450-0155 & 450-0156) for simple connectivity w/ NXP i.MX 6 and other platforms

LSR is the leader in Wireless Product Development, offering true end-to-end solutions through its array of services and technical expertise.



### Design Services

LSR delivers complete system solutions from concept to manufacturing. We are your wireless M2M solutions partner, providing complete turnkey services and solutions.

- RF Design/Engineering
- Software/Firmware Design
- Antenna Design
- Industrial Design
- Mechanical Engineering



### EMC Testing & Certification

At LSR, we understand it is critical for your company to have a compliant product supported by the appropriate documentation, ready for deployment into the market. LSR provides the experience and knowledge to provide quality test services that meet your timeline and budget.

- On-Site FCC / IC /CE EMC Certification
- Wireless & Antenna Testing
- EMC Testing
- International Testing Services



### Wireless Products

LSR offers the fastest, lowest cost way to add wireless capabilities to your product concept. LSR's fully-certified modules and antennas accelerate your time-to-market and support the full breadth of communication technologies, including:

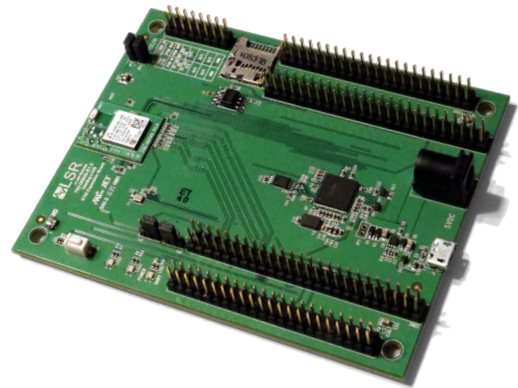
- Wi-Fi®
- Bluetooth®
- Bluetooth® Smart
- ZigBee®
- 802.15.4 & proprietary protocols

Sterling-LWB NB\_v2\_1

# HARNESS THE STERLING-LWB™ FOR EMBEDDED WI-FI® AND BLUETOOTH® LOW ENERGY APPLICATIONS

## Introducing the **STERLING-LWB for WICED™** Reference Platform

You can now leverage the high-performance Sterling-LWB™ module for embedded MCU applications as well! The Sterling-LWB for WICED™ reference platform provides a very simple and fast way to add both Wi-Fi and BLE v4.1 connectivity to your microcontroller-based design utilizing the power of Cypress' robust WICED™ software development kit. The low cost, pre-certified Sterling-LWB is now validated with the STM32F411 MCU and can be migrated to other popular MCU's, giving you unmatched speed in adding Wi-Fi and BLE to your application. This comprehensive reference platform features a carrier board for easy connectivity with the STM32F411 Discovery Kit, extensive documentation and software examples, TiWiConnect™ cloud connectivity and ModuleLink™ mobile app for easy development and integration.



*Sterling-LWB for WICED™ Carrier Board (450-0173)*



### Utilize the Popular WICED™ SDK by Cypress

Accelerate your WICED™ application development with extensive software examples and source code, including BLE profiles, BLE for Wi-Fi commissioning, Power Management, and more.



### ModuleLink™ Mobile App for Easy Evaluation

The ModuleLink™ Mobile App for Android lets you connect immediately to the Sterling-LWB from your mobile for easy evaluation and testing.



### TiWiConnect

Module | Cloud | App

### Cloud-Ready with LSR's TiWiConnect™

With a free TiWiConnect™ developer account and web portal, you can quickly demonstrate full Wi-Fi-to-Cloud functionality.

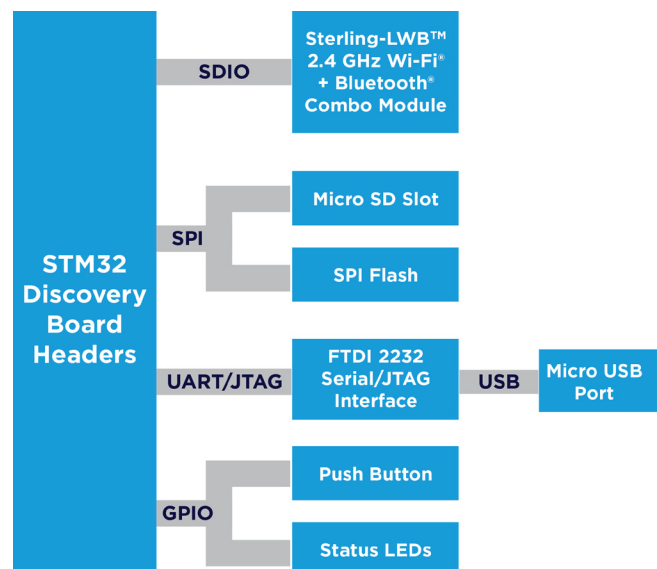
## Take advantage of the platform's many Wi-Fi-to-Cloud sample applications, including:



3-AXIS GYROSCOPE AND ACCELEROMETER



LED CONTROL AND STATUS



*Sterling-LWB for WICED™ Carrier Board Block Diagram*